

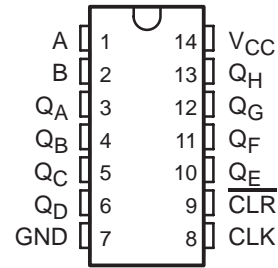
SN74ALS164A

8-BIT PARALLEL-OUT SERIAL SHIFT REGISTER

SDAS159D – APRIL 1982 – REVISED DECEMBER 1994

- AND-Gated (Enable/Disable) Serial Inputs
- Fully Buffered Clock and Serial Inputs
- Direct Clear
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs

D OR N PACKAGE
(TOP VIEW)



description

This 8-bit parallel-out serial shift register features AND-gated serial (A and B) inputs and an asynchronous clear ($\overline{\text{CLR}}$) input. The gated serial inputs permit control over incoming data because a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level input enables the other input, which determines the state of the first flip-flop. Data at the serial inputs can be changed while the clock is high or low, provided that the minimum setup-time requirements are met. Clocking occurs on the low-to-high-level transition of the clock (CLK) input. All inputs are diode clamped to minimize transmission-line effects.

The SN74ALS164A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS				OUTPUTS†		
$\overline{\text{CLR}}$	CLK	A	B	QA	QB ... QH	
L	X	X	X	L	L	L
H	L	X	X	QA0	QB0	QH0
H	↑	H	H	H	QAn	QGn
H	↑	L	X	L	QAn	QGn
H	↑	X	L	L	QAn	QGn

† QA0, QB0, QH0 = the level of QA, QB, or QH, respectively, before the indicated steady-state input conditions were established.

H = high level (steady state), L = low level (steady state)

X = irrelevant (any input, including transitions)

↑ = transition from low to high level

QAn, QGn = the level of QA or QG before the most recent

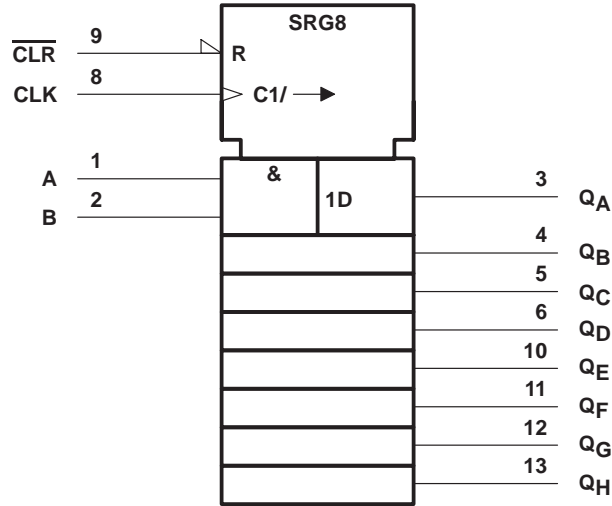
↑ transition of the clock; indicates a 1-bit shift.

SN74ALS164A

8-BIT PARALLEL-OUT SERIAL SHIFT REGISTER

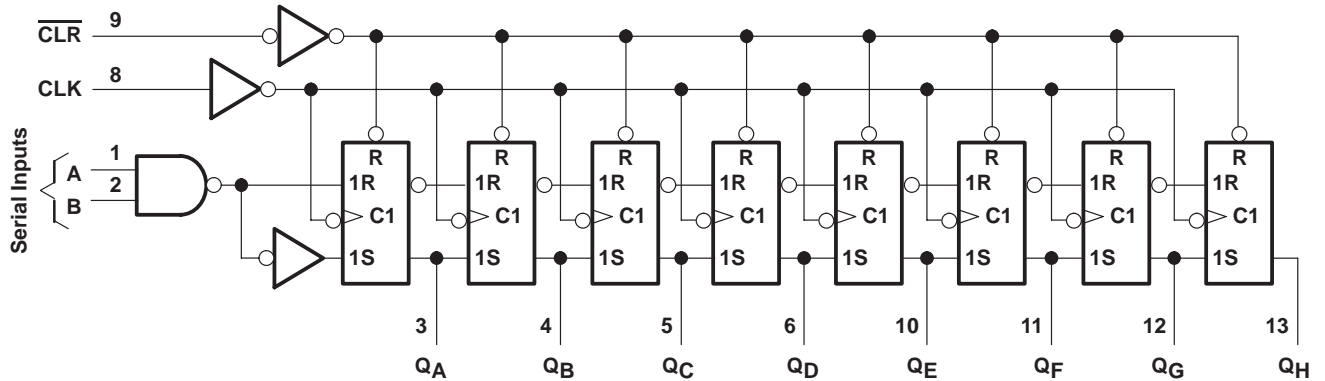
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

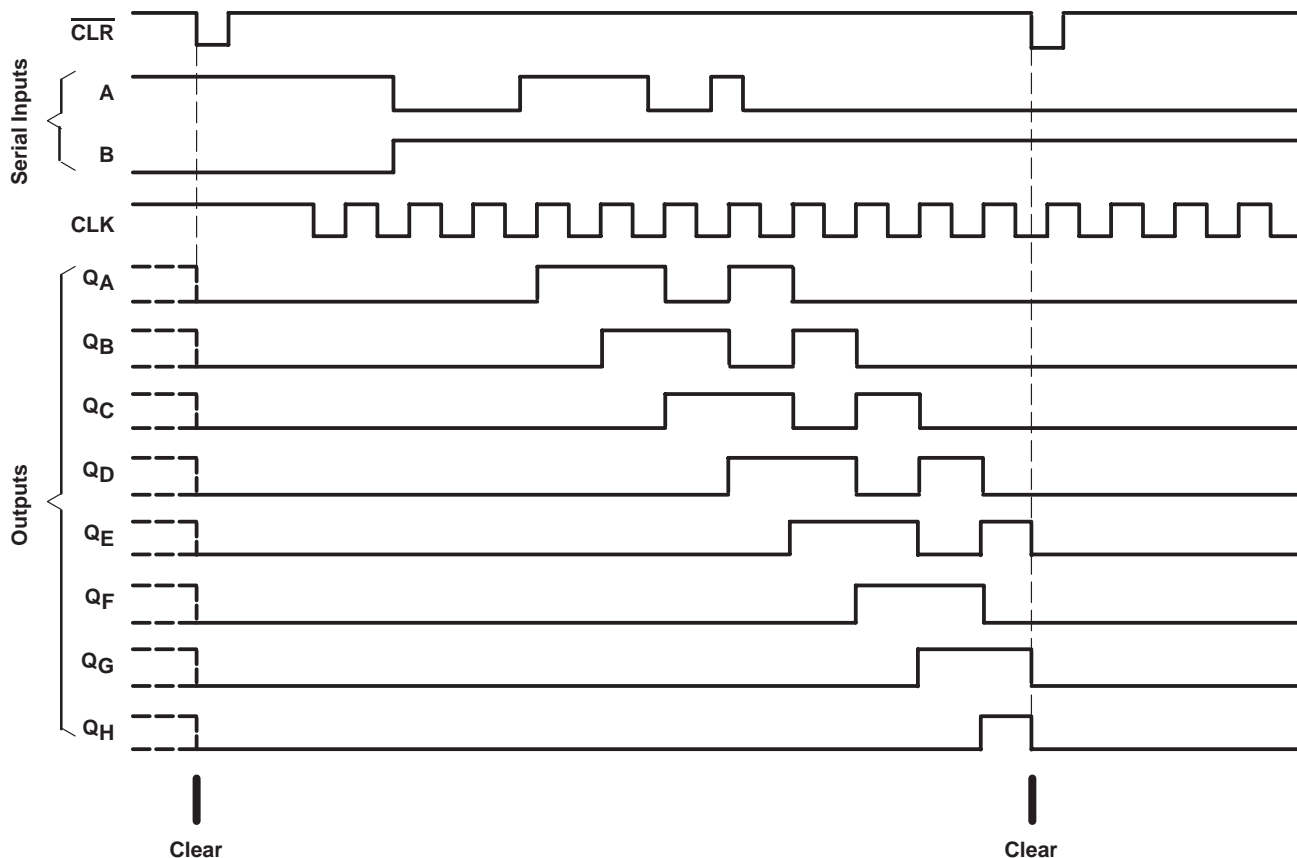
logic diagram (positive logic)



SN74ALS164A 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTER

SDAS159D – APRIL 1982 – REVISED DECEMBER 1994

typical clear, shift, and clear sequences



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



SN74ALS164A

8-BIT PARALLEL-OUT SERIAL SHIFT REGISTER

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recommended operating conditions

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current			-0.4	mA
I _{OL}	Low-level output current			8	mA
f _{clock}	Clock frequency			50	MHz
t _w	Pulse duration	CLK	10		ns
		CLR low	16		
t _{su}	Setup time before CLK↑	Data	6		ns
		CLR inactive	8		
t _h	Hold time, data after CLK↑	2			ns
T _A	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.5	V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -0.4 mA	V _{CC} - 2			V
V _{OL}	V _{CC} = 4.5 V, I _{OL} = 4 mA		0.25	0.4	V
			0.35	0.5	
I _I	V _{CC} = 5.5 V, V _I = 7 V			0.1	mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V			20	μA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V			-0.1	mA
I _O ‡	V _{CC} = 5.5 V, V _O = 2.25 V	-30		-112	mA
I _{CC}	V _{CC} = 5.5 V, See Note 1		14	24	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.
 NOTE 1: With 4.5 V applied to the serial input and all other inputs, except the CLK, grounded, I_{CC} is measured after a clock transition from 0 to 4.5 V.

switching characteristics (see Figure 1)

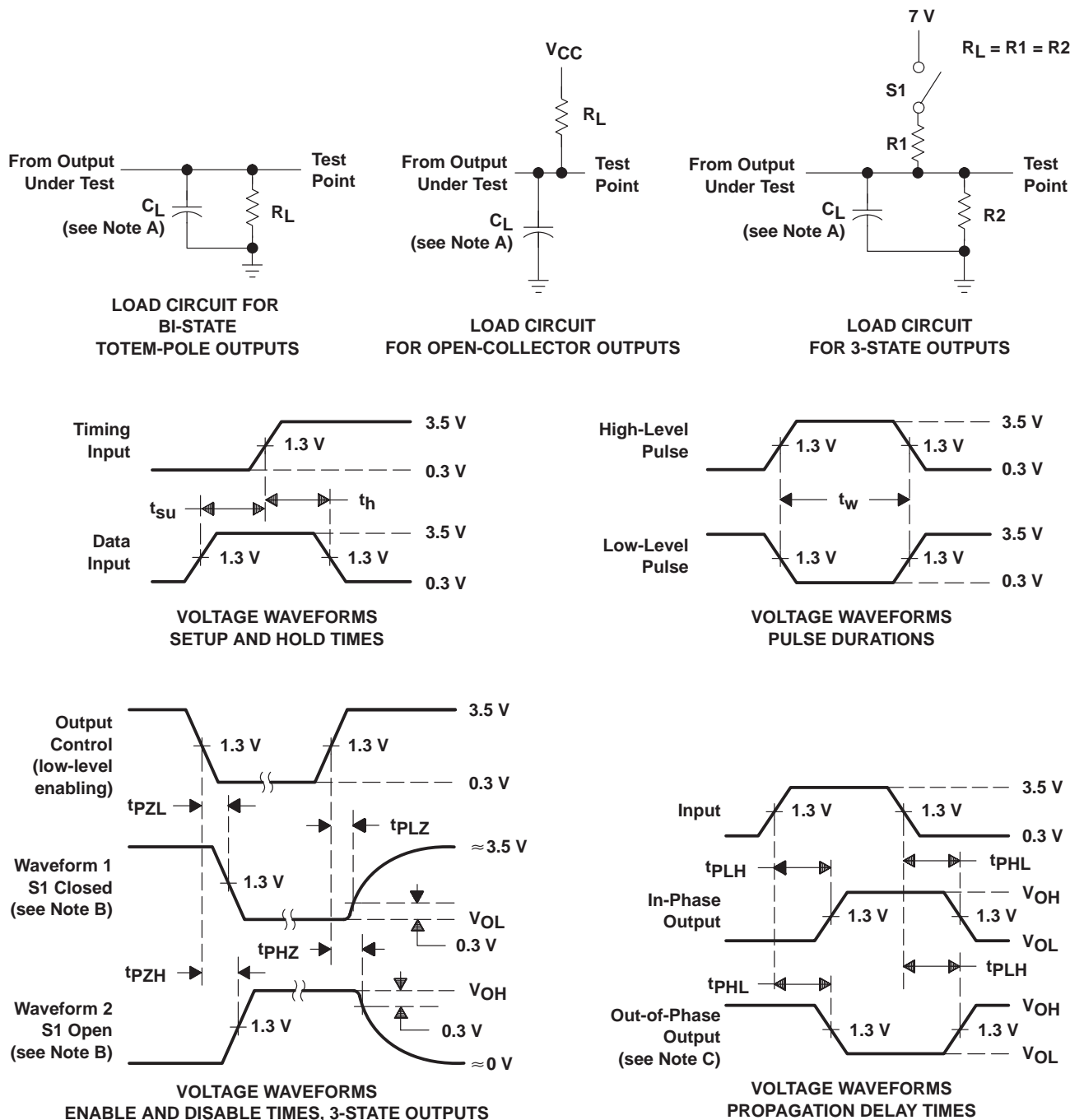
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX§			UNIT
			MIN	TYP¶	MAX	
f _{max}			50	75		MHz
t _{PHL}	CLR	Any Q	6	15	20	ns
t _{PLH}	CLK	Any Q	4	9	16	ns
t _{PHL}			5	11	17	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

¶ All typical values are at V_{CC} = 5 V, T_A = 25°C.



PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS164AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	ALS164A	
SN74ALS164ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS164A	Samples
SN74ALS164AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS164AN	Samples
SN74ALS164ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS164A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

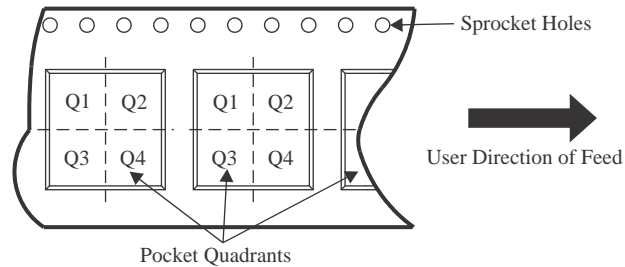
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS164ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS164ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS164ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74ALS164ANSR	SO	NS	14	2000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ALS164AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74ALS164AN	N	PDIP	14	25	506	13.97	11230	4.32

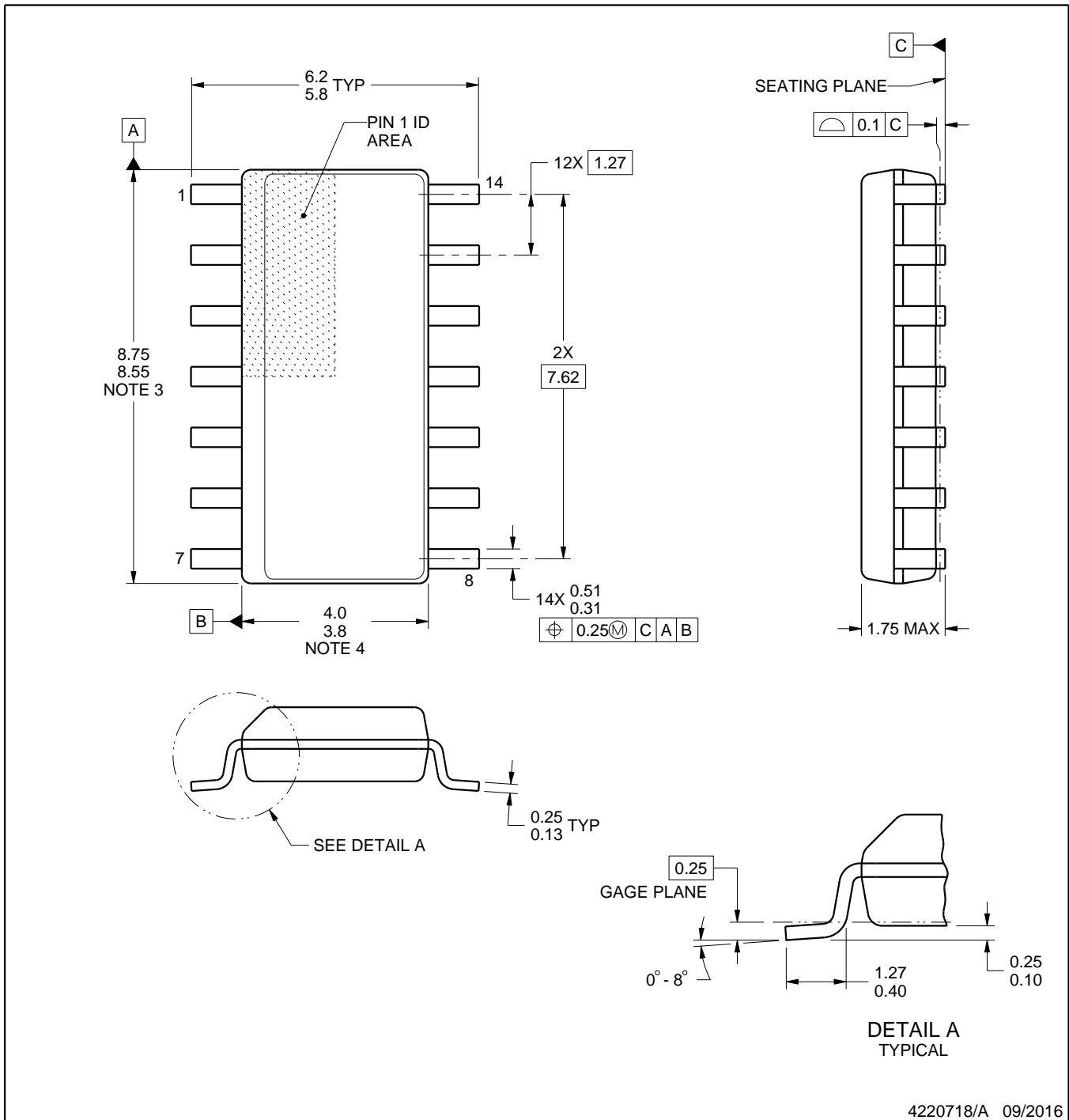
D0014A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

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